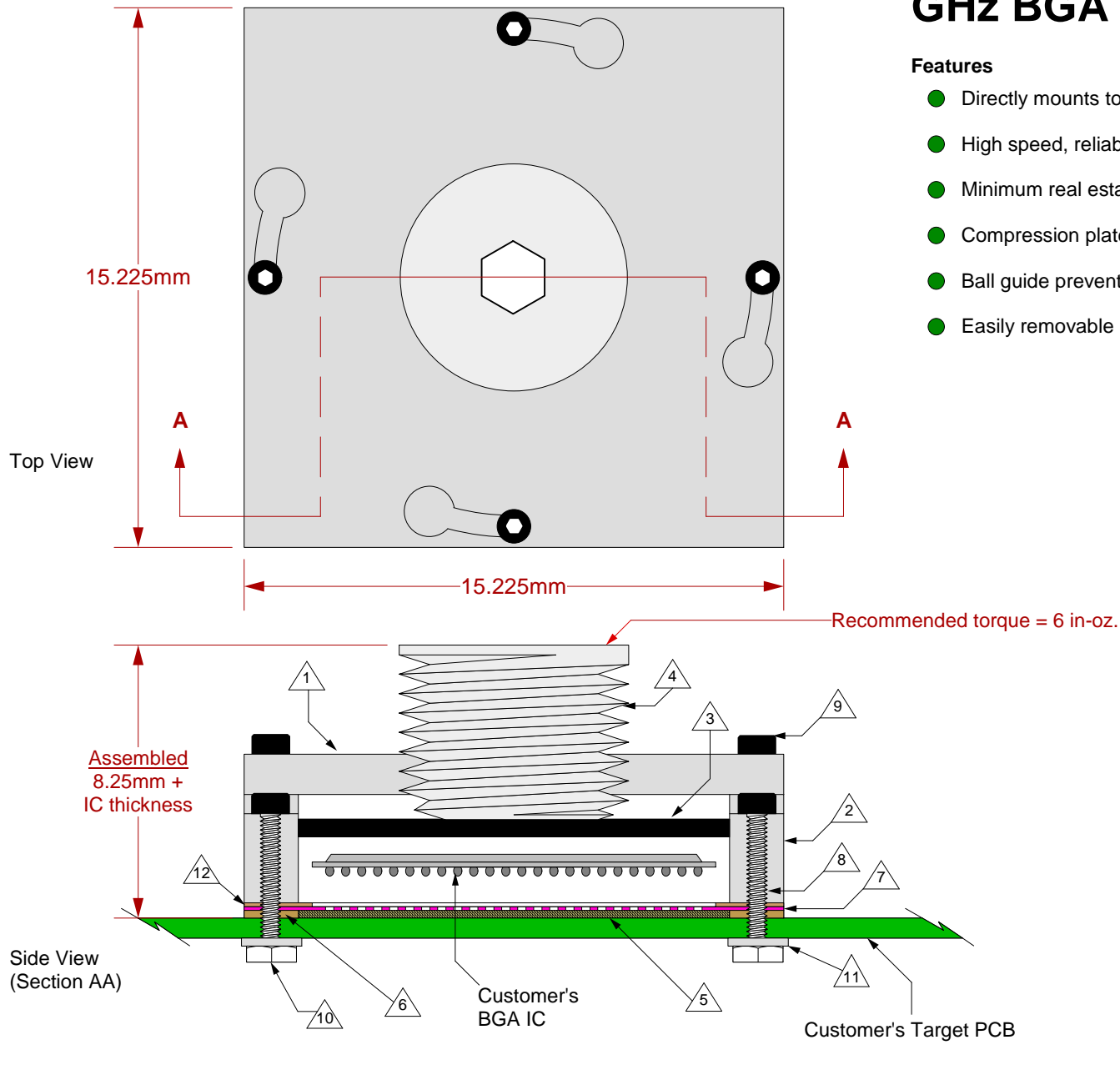



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Cirlex. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.
- 12 IC Guide: Torlon

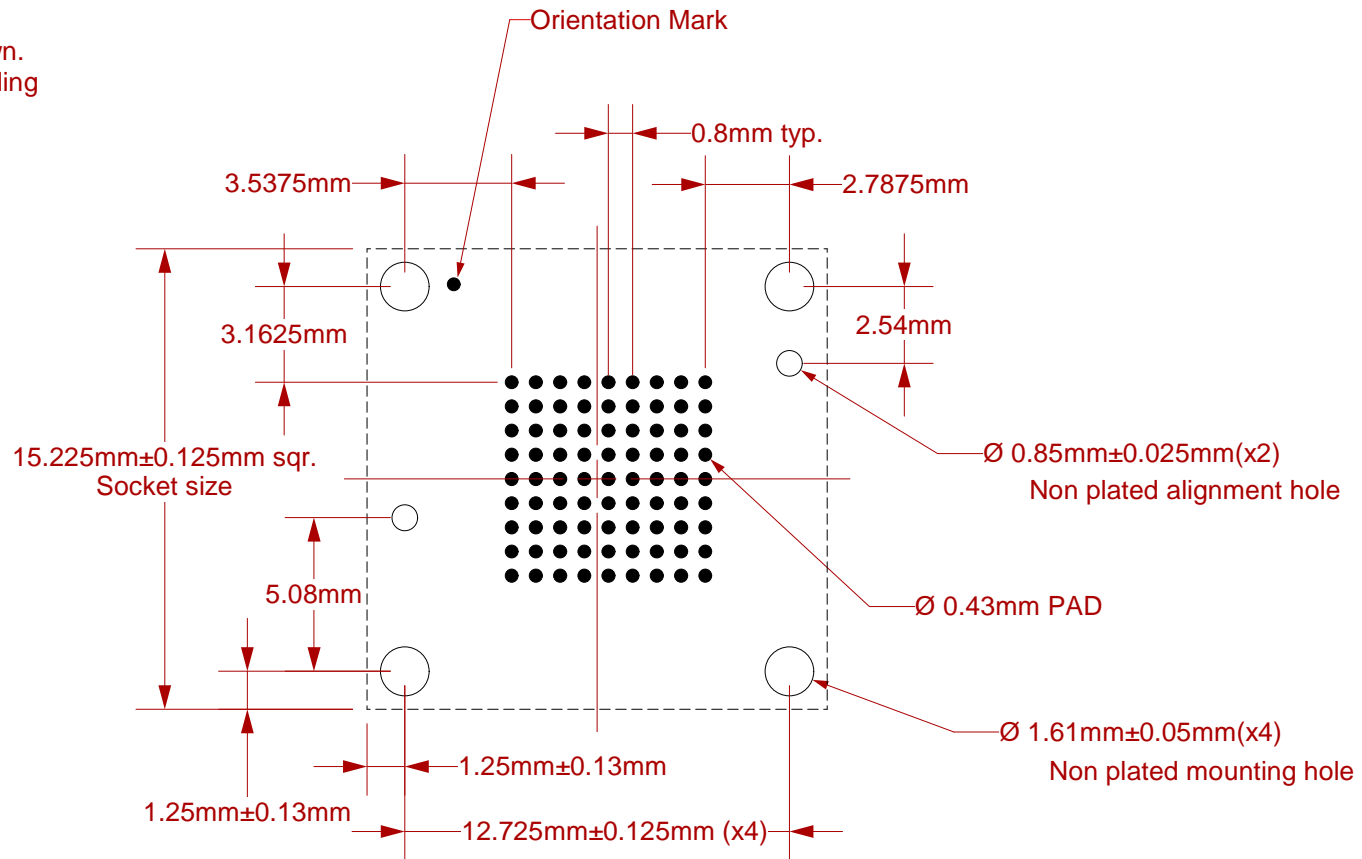
	SG-BGA-6149 Drawing	Status: Released	Scale: -	Rev: C
	© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 3/23/05
		File: SG-BGA-6149 Dwg	Modified: 04/10/14	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**


Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

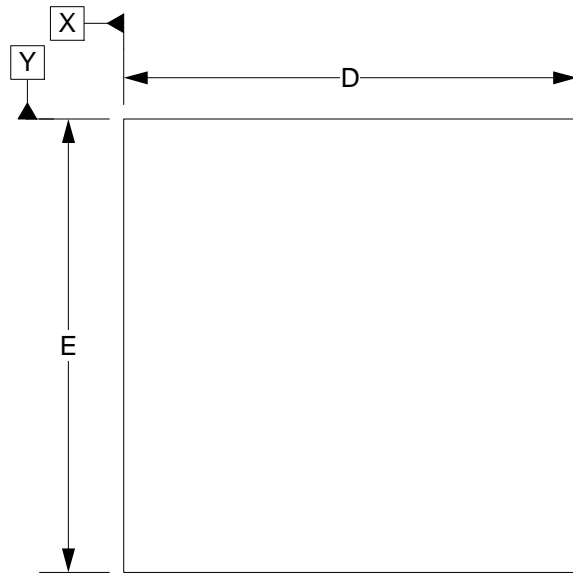


Target PCB Recommendations

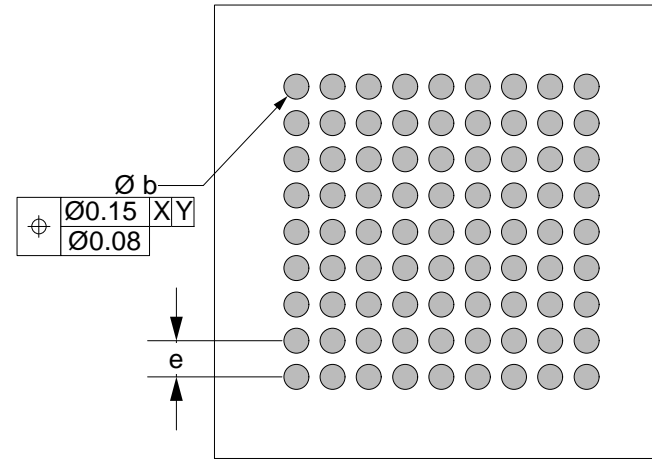
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

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	<p>Drawing: H. Hansen</p>		<p>Date: 3/23/05</p>		
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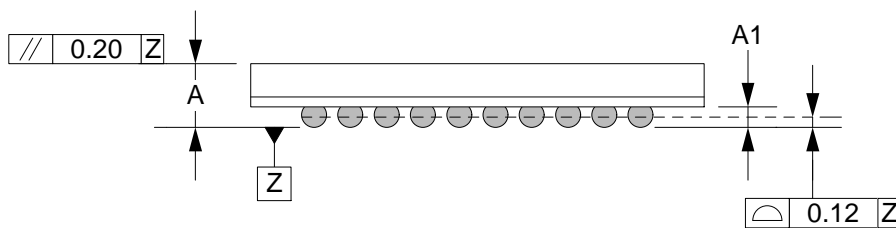


Top View



Bottom View

Array: 9x9



Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.



Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z .




Datum Z (seating plane) is defined by the spherical crowns of the solder balls.



Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.15
A1	0.27	0.37
b		0.47
D	9.0 BSC	
E	9.0 BSC	
e	0.8 BSC	

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	Drawing: H. Hansen	Date: 3/23/05		
	File: SG-BGA-6149 Dwg	Modified: 04/10/14		